

February 7, 2021

Dear Prospective Sponsor/Exhibitor:

We are pleased to extend to you and your company the opportunity to exhibit and sponsor events at the co-located 2021 IEEE International Pulsed Power Conference (PPC) and IEEE Symposium on Fusion Engineering (SOFE). We are expecting this to be an IN-PERSON meeting given the projection of waning COVID-19 restrictions. Both conferences are fully (financially & technically) sponsored by the IEEE Nuclear and Plasma Sciences Society (NPSS). This is the second time the PPC and SOFE have co-located, first being in 2015 at the Austin Downtown Hilton in Austin, Texas. With the current state of COVID-19, the expected attendance of the co-located conferences is ~450 attendees but with some luck, it may be closer to our estimates prior to COVID-19 (~750 attendees).

PPC has a history dating back to 1976 and this bi-annual conference provides a premier forum for the exchange and dissemination of technical information on pulsed power technology and engineering. The meeting is organized by the NPSS's Pulsed Power Science and Technology (PPS&T) subcommittee. Typically, more than 25 different countries submit abstracts and present papers, validating the truly international nature of the conference and its participants. The 3.5-day event consists of oral/poster presentations and technical discussions across all areas of pulsed power science, technology, and applications. Recent Pulsed Power Conferences have had especially strong technical contributions in the areas of biological and medical applications. The typical pulsed power attendance is ~450 -550 attendees on its own. SOFE is a biennial event that is organized and sponsored by the Fusion Technology Standing Committee of the IEEE NPSS with typical attendance of ~250-350 people. The meeting highlights advances in magnetic and inertial fusion energy science and engineering. The conference focuses in technical areas including fusion development in both large R&D experimental fusion reactor facilities and basic research in fusion concepts, systems, components and materials.

This co-located conference will be held in Denver, Colorado, on <u>December 12 - December 16, 2021</u> which is delayed from the original dates of May 31 - June 4, 2021 to encourage higher turnout and ensure the safety of all participants. It will be held at the Denver Downtown Sheraton hotel in the heart of downtown. Booth space for the exhibitors is planned for a large 21,000 sq. ft. exhibit area located directly outside three presentation rooms and the poster session area. While we are working with local officials on the best way to implement conference food and beverage breaks including the Sunday night reception in the most appropriate and safe manner, we will do our best to make sure exhibitors see foot traffic to the greatest extent possible. Furthermore, we will be increasing font size of names on attendee's badge as well as adding a QR code to accommodate sharing of contact information (if they so choose). These are changes from previous conferences due to feedback we received from exhibitors and attendees. Please continue to share with us ways to improve our conference!

Being a conference exhibitor or sponsor is a tremendous way to expose your company to a broad spectrum of industrial, government, and university organizations and a way to prospect for both immediate and future business. Your competitors will likely be there, and we sincerely hope you will too! Please see the enclosed Exhibitor and Sponsorship Prospectus for specific details on how your company can participate. There are limited exhibitor booths and sponsor events available and you are therefore encouraged to sign up as soon as possible in order to receive your preferred choices. Priority for booth location and event sponsorship choices will be given on a first come, first served basis based on the receipt date of the application and accompanying reservation deposit. We will be creative in drawing participants to all areas of the exhibit area to make all our sponsors and/or exhibitors visible and accessible. What we show here will likely change but we are doing our best to keep it as close to this as possible and as normal as possible.

Your contribution and involvement as a Sponsor and/or Exhibitor are vital to the continued success of our conference and our goal is to give everyone the ability to benefit from this event by providing the potential for both business opportunities as well as knowledge transfer. We are excited to include you in the co-located 2021 IEEE PPC-SOFE conference. The website to sign up, accessed via the conference website https://uta.engineering/ppcsofe2021/, will go live at 12 PM EST on March 1, 2021. We look forward to your participation and a successful conference for everyone.

Sincerely.

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SPONSORSHIP AND EXHIBITOR PROSPECTUS

With the large number of both domestic and international organizations expected to attend the 2021 PPC-SOFE meetings, there is abundant opportunity for prospecting of both immediate and future customers. Past participant attendees to the PPC-SOFE have included the following affiliations:

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ABB Switzerland Ltd.	•	_
	Continental Electronics Corp.	High Current Electronics Institute High Energy Accelerator Research
Agency for Defense Development Air Force Office of Scientific Research	Cornell University	ļ ^
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Air Force Research Laboratory	Dana Corp.	Hofstra University
Alameda Applied Sciences Corp.	Dawonsys	Honeywell FM&T
Alcon Laboratories	Dean Technology Inc.	Huazhong Univ. of Science & Tech.
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Clemson University	GSI Darmstadt	Ktech Corporation
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Coherent	Helmut-Schmidt-University	Kyushu Institute of Technology
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Bird RF Eagle Harbor Technologies Montena Technology	Bird RF		Montena Technology
AVX Corporation Scientific Applications and Res. Assoc. Jema Energy	AVX Corporation	Scientific Applications and Res. Assoc.	Jema Energy
VR Electronics Co LtdMetglas Inc.Suematsu Electronics	VR Electronics Co Ltd	Metglas Inc.	Suematsu Electronics









Please understand much of this is the original exhibitors plan we had prior to the pandemic. We want to update it with the latest possible layout from the hotel with restrictions considered but it is constantly changing as COVID changes and what is required today will hopefully not be required in December 2021. Right now, we are assured we can fit between 35 and 44 booths in the planned space but it may not be along the wall as it is shown here. If we wait much longer to get this out we fear not giving you enough notice so we are sending this out to give you an idea of what the space looks like, what was originally planned, and from it, we hope you will help us to make this a success for all. What is shown here could be representative of how it will be in December 2021 and much of it could also be subject to change pending the status of COVID as we get closer. Our goal is to keep it as close to a normal event as possible! We will make every effort to get you as much foot traffic as possible, we will be as transparent as possible, and we will keep you updated on changes we learn of as we learn of them! Your participation is critical to our success so we plan to be in this together!

This year's items are focused on individual exhibitor booth packages and other sponsorship opportunities.

BOOTH SPACE

Both conference's meeting space will all be confined to the basement level of the hotel. Oral sessions will be conducted within the Plaza Ballroom D/E/F and the Governor's Square meeting rooms. The poster sessions for both conferences will be located within the Plaza Ballroom A/B/C. All food and beverage events, including receptions and coffee breaks, will occur within the Plaza Exhibit/Foyer area that is shared with the Sponsors/Exhibitors. The diagrams below show the hotel meeting space and their proximity to the exhibit/foyer. As shown, the Plaza ballroom space is directly adjacent to the exhibit/foyer area and the flow of traffic will force attendees through this area as they come in and out of the meeting space. There are two main entrances into the exhibit/foyer area. These include the escalators that connect the meeting space to the main hotel lobby as well as the two elevator banks that bring people to and from the Main Building and Tower Building, respectively. The 2018 IEEE ICOPS meeting, an annual meeting organized by the Plasma Science and Applications (PSAC) subcommittee of NPSS, was held at this same hotel in June 2018. The meeting space was well reviewed by the exhibitors and attendees as a very concise with ample space and flow through the common areas. Booth numbers will be provided early to allow for time to add it to any promotional materials.

The Exhibit/Foyer area is over 21,000 square feet and it will be shared by the exhibit booths and the food and beverage area. A diagram of this space with the booth layout and booth ID numbers is located on the page following the overall hotel and conference space floor plan.

Each booth will include a 7' (2.1 m) high draped back wall and 3' (0.9 m) high draped side rails, one 6' (1.8 m) draped table, two contour chairs, and one wastebasket, and a 7" \times 44" (0.2 \times 1.1 m) single line, company identification sign.

Assignment of booths will be done on a first come, first served basis determined by the receipt date of the registration and deposit. Exhibitors are encouraged to visit the conference website for updates and assignments which will be kept current as much as possible.

Exhibitors will be informed as to when booth registrations will be possible. Booth reservations can then be done online (via https://uta.engineering/ppcsofe2021/) or by submitting the form on the back of this prospectus.







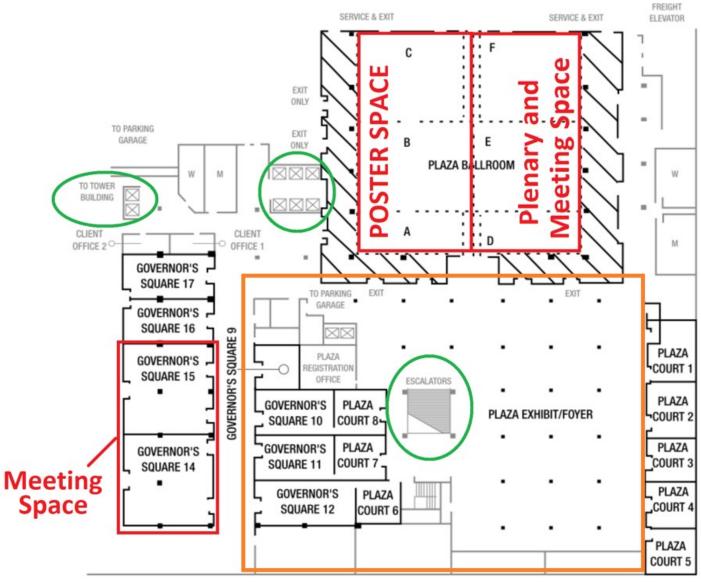


EXHIBIT HOURS

Tentative Exhibit area hours are as follows:

Event	Day	Start	End
Contractor Move-In	Sunday, December 12, 2021	10:00 AM	5:00 PM
Exhibitor Move-In	Sunday, December 12, 2021	10:00 AM	5:00 PM
Sunday Night Reception	Sunday, December 12, 2021	5:30 PM	7:30 PM
Exhibit Hours	Monday, December 13, 2021	7:30 AM	12:00 PM
Exhibit Hours	Monday, December 13, 2021	1:30 PM	5:00 PM
Exhibit Hours	Tuesday, December 14, 2021	7:30 AM	12:00 PM
Exhibit Hours	Tuesday, December 14, 2021	1:30 PM	5:00 PM
Exhibit Hours	Wednesday, December 15, 2021	7:30 AM	12:00 PM
Exhibit Hours	Wednesday, December 15, 2021	1:30 PM	3:30 PM
Exhibitor Move-out	Wednesday, December 15, 2021	3:30 PM	7:00 PM

Vendors are expected to have at least one Exhibitor at their booth during the Exhibit hours listed above.



The area highlighted in the orange box is the area that is highlighted in the next figure. The next figure is rotated 90 degrees counterclockwise to this one. We apologize for this confusion, but it is how the images are provided by GES.

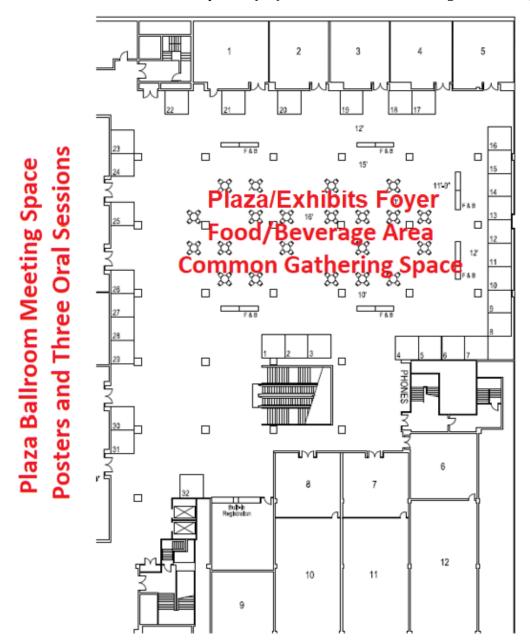








The figure below shows the booth layout planned for the Exhibits area; booths labeled 1 - 31. In this case, the Plaza Ballroom oral/poster space is located to the left of the figure and the Governor's Square oral meeting rooms are located below. Thirty-One (31) booths have been arranged in this space.



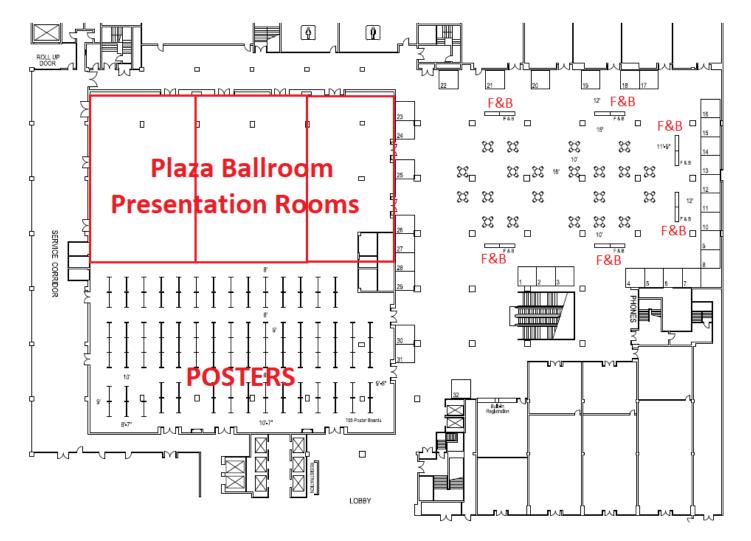
Governor's Square Meeting Rooms are Above and Below Here We are using Rooms 14 and 15 below as Parallel Session Rooms











Governor's Square Meeting Rooms in this Hallway

This figure is rotated 90 degrees counterclockwise with respect to the first figure and the same as the previous figure. This Figure highlights the orientation of the posters and the location of the plenary meetings and the three parallel meeting rooms, all of which are held in the plaza ballroom presentation rooms.

FOOD AND BEVERAGE BREAK HOURS

Food and beverage are subject to change significantly due to social distancing and contact restrictions. Originally the plan was for food and beverages throughout the conference to be served in the Exhibits/Foyer area allowing significant potential for interfacing with attendees to showcase your company's products and solutions. These events include the Sunday night reception as well as breakfast, a morning break, and an afternoon break for each of the three days of the main conference events. These events will provide over 8 hours of time for directly interacting with conference attendees. Our objective is to be sure that all attendees have ample opportunity to view the booths and interact with you during the overall conference.









Tentative Food and Beverage Event hours in the Exhibits Area are as follows:

Event	Day	Start	End	
Sunday Night Reception	Sunday, Dec. 12, 2021	5:30 PM	7:30 PM	
Coffee Tables (3 Days)	Mon-Wed, Dec. 13 - 15, 2021	7:30 AM	8:30 AM	
Morning Break (3 Days)	Mon-Wed, Dec. 13 - 15, 2021	9:30 AM	10:00 AM	
Afternoon Break (3 Days)	Mon-Wed, Dec. 13 - 15, 2021	3:00 PM	3:30 PM	

BOOTH PACKAGE

This year we are offering the following exhibit booth package:

• Single Booth (\$5000) – 1 Booth and 2 Full Registrations

The two Full Registrations include entrance and participation in the Sunday night reception and all Technical Sessions. Additional exhibitors must register if they wish to attend the technical sessions. Tickets for additional exhibitors to attend the social events, banquet and night out, can be purchased online or at the conference.

• Lower cost options will be considered, such as a simple tabletop display, on an as needed basis so we encourage exhibitors to contact the Exhibitor Co-Chairs with these requests.

Single Booth Package (\$5000):

- One draped booth space from Sunday to Thursday during the conference.
- Inclusion on the Sponsor Page of the Proceedings.
- Inclusion of a Sponsor-provided one-page cut sheet in the Registration Package for conference attendees.
- Logo on the inside of the Pocket Program.
- Logo in the Mobile App if the app developer enables that feature
- Logo included on signage in the Conference meeting space area.
- Linked (to your company URL) website banner ad on the Exhibitors page. Ad will run from date of signed contract through conference end date and as long as the conference page is live.
- Two complementary full registrations to the Conference (Night Out and Thursday night banquet tickets can be purchased at the same subsidized cost available to general attendees).
- Attendee name badges will be double sided for easy viewing, text will be as large and readable as possible, and we will make every effort to add the QR code capability to easily get the contact information they are willing to share. On the registration page, we will place a check box to allow the attendees to share contact information with our Sponsors/Exhibitors.

EVENT AND OTHER SPONSORSHIP PACKAGES

There are many additional sponsorship opportunities including these below. We have attempted to capture a few new ones given the COVID-19 pandemic, but there are certainly others we have missed.

- PLATINUM FLOOR SOCIAL DISTANCING SIGNAGE COVID-19 has brought about the need for near countless signage reminding people to stand 6 feet away from each other and maintain social distancing. There will be need for floor decals for people to stand at reception, F&B, and exhibitor booths. Your company logo will be displayed on the floor signage throughout the conference space.
- PLATINUM VERTICAL SOCIAL DISTANCING SIGNAGE
 COVID-19 has brought about the need for near countless signage reminding people to maintain 6 feet away from each other. There will be need for directional signage throughout the conference space directing attendee traffic and reminding them to stand 6 feet away from each other while standing. These will be vertical signs throughout the conference space for people to see as they are walking. Your company logo will be prominently displayed on all the vertical signage









\$15,000

\$15,000

•	PLATINUM – HAND SANITIZER COVID-19 has reminded us the importance of hygiene. We buy personal hand sanitizers to hand out to attendees and your company logo will be labeled on the bottles.	\$10,000
•	PLATINUM – FACE MASKS	\$15,000
	COVID-19 has given us the pleasure of wearing a face mask. We will buy branded face masks with the PPC-SOFE logo and your company logo to be give out.	Ψ13,000
•	PLATINUM – NIGHT OUT SPONSORSHIP – PENDING COVID STAUS AS WE GET CLOSER	\$20,000
	Scheduled on one night of the conference, this is 2 - 3 hours of high visibility. As the exclusive sponsor of this event, your company's logo will be included on all printed signage and materials promoting this event. You will also have the opportunity to give a few minute welcoming remark to the audience.	
•	PLATINUM - CONFERENCE PROCEEDINGS	\$20,000
	Be the sponsor whose logo is on the USB Conference Proceedings received by all registered attendees! These Proceedings have an exceptionally long shelf life as attendees use them as reference material. Your logo will be on the drive and the home screen of the proceedings on the drive.	
•	PLATINUM - CONFERENCE WI-FI	\$15,000
	We will make your company name the WI-FI password and put your logo on the initial connect screen.	
•	GOLD- NIGHT OUT BUS TRANSPORTATION	\$7,500
	Logo/Name displayed prominently in the conference literature and inside the busses.	
•	GOLD- COLOR PROGRAM ADVERTISEMENT	\$2,500
	This is already included with the purchase of a booth, but should you want this alone	
	without a booth, this is a full page color advertisement in the conference handout	
	booklet.	
•	SILVER – SWAG BAG PROMO MATERIAL	\$2,000
	This is already included with the purchase of a booth but should you want this alone	
	without a booth.	
•	SILVER – MOBILE APP	\$2,000
	Logo/Name displayed prominently in the conference literature and on the splash screen	
	of the mobile app used by all attendees.	.
•	SILVER - LANYARDS	\$2,000
	Logo/Name on lanyards, distributed to all conference attendees.	
•	SILVER - CHARGING STATION	\$2,500
	Logo/Name at charging station in main conference lobby / coffee area.	1, m
•	SILVER – B&W PROGRAM ADVERTISEMENT	\$1,500
	Full page of B&W printed advertisement in the conference handout book.	
•	SILVER – COMPANY NAME ON WEBSITE AND PROGRAM	\$1,000
	Full page of B&W printed advertisement in the conference handout book.	

Please contact Richard Ness (rness1@ieee.org), Sterling Beeson (sterling.beeson@ieee.org), David Wetz (wetz@uta.edu), or Kevin Freudenberg (freudenbergk@ornl.gov) if you have any additional ideas on how your organization might like to participate.

Have any other ideas for sponsorship?

How can we better help to promote your products and/or services? If you have any additional ideas for sponsorship concepts, promotions, or items that we can potentially provide you to make your job more effective and your conference more productive, please don't hesitate to contact Richard Ness (rness1@ieee.org) or Sterling Beeson (sterling.beeson@ieee.org).









TERMS AND CONDITIONS:

1. Contract

This application, properly executed by Applicant (Exhibitor) shall upon written acceptance by 2021 PPC-SOFE management constitute a valid and binding contract.

2. Assignment of Space

Assignment of space to exhibitors and those making application will be made in the order of date of receipt of contract application and required deposit. 2021 PPC-SOFE will continue to receive applications and assign exhibit space, as it remains available, until shortly before the show opening date. In all cases, total booth payments must be received prior to show opening.

2021 PPC-SOFE assignment of booths is final and shall constitute an acceptance of the Exhibitor's offer to occupy space unless something changes due to restrictions imposed by COVID 19. Due to the necessity of being flexible with the changing local health regulations, 2021 PPC-SOFE management will retain the chronological order of receipt of contract application and required deposit. If the booth layout and/or number of booths require modification in a significant fashion because of COVID restrictions, Exhibitors will be contacted in this order and be given the option of changing the assignment of space or offered a refund. After assignment is made, space location may not be changed unless we are forced to change it due to COVID restrictions. The exhibitor may not transfer or cancel except upon written request and with the subsequent written approval of 2021 PPC-SOFE management. 2021 PPC-SOFE management reserves the right to reassign Exhibitor space to modify floor plan for overall benefit of the show and to meet health and safety requirements.

3. Subletting Space

No exhibitor will assign, sublet, or apportion the whole or any part of the space allotted to him, nor exhibit therein, nor permit any other person or party to exhibit therein, any other goods, apparatus, etc. not manufactured or distributed by the Exhibitor in the regular course of his business except upon prior written consent of 2021 PPC-SOFE Management. Space reductions are considered cancellations and may be subject to cancellation fees.

4. Exhibit Space Rental Rates

Exhibit space rental includes materials and services described herein. Show price per 8 x 10 ft (2.4 x 3 m) space contracted at \$5,000 for one booth includes booth space without equipment.

5. Payment Requirements and Cancellation Charges

Applications require a 50% deposit before booths are assigned. Payment in full is required by September 30, 2021. All applications received after October 1, 2021 must be accompanied by full payment.

All cancellations must be made in writing and will be based on the following schedule of refunds:

Before October 15, 2021 - Refund Less \$1000 processing fee On or after October 16, 2021 - No Refund

It is understood that 2021 PPC-SOFE reserves the right, at its option, to reassign a cancelled booth regardless of the cancellation rate assessed. In the event that the premises in which the 2021 PPC-SOFE Show is conducted shall become, in the sole discretion of 2021 PPC-SOFE, unfit for occupancy, or substantially interfered with by reason of any cause or causes not reasonably within the control of 2021 PPC-SOFE, this agreement may be terminated by 2021 PPC-SOFE. For this purpose, the term "cause or causes" shall include, but not by way of limitation, fire, flood, epidemic, earthquake, explosion or accident, blockage, embargo, inclement weather, governmental restraints, restraints or orders of civil defense, or military authorities, act of public enemy, riot or civil disturbance, strike, lockout, boycott or other labor disturbance, inability to secure sufficient labor, technical, or other personnel, failure, impairment or lack of adequate transportation facilities, inability to obtain, or condemnation, requisition or commandeering of necessary supplies or equipment, local, state or federal law, ordinance, rule, order, decree or regulation, whether legislative, equipment, local, state or federal law, ordinance, rule, order, decree or regulation, executive, or



 $judicial, and \ whether \ constitutional, or \ act \ of God.$

Should 2021 PPC-SOFE terminate this agreement pursuant to the provision of this paragraph the Exhibitor waives any and all claims for damages and agrees that 2021 PPC-SOFE may, after computing

the total amount of 2021 PPC-SOFE cost and expenses in connection with its preparation for and conducting of the 2021 PPC-SOFE Event, (including a reasonable reserve for claims and other contingencies), refund to the exhibitor, as and for complete settlement and discharge of all said Exhibitor's claims an demands, and amount which bears the same relationship to the fee paid by said Exhibitor as the total refundable amount as computed above bears to the total amount of fees paid by all exhibitors.

3. Going Virtual

Should 2021 PPC-SOFE have to go Virtual due to COVID restrictions, there will be virtual tiers equivalent to the current level of sponsorship. Your exhibitor/sponsor status will automatically convert to the virtual level. The exhibitor will have two weeks from the time of the formal announcement to request a full refund or accept the virtual conversion.

4. Exhibit Booth Manning and Dismantling Schedule

A representative must man exhibit space during all times when Exhibition is officially open. Exhibit space must be maintained in a neat and orderly manner throughout the Exhibition. Exhibitors may begin dismantling only after hours stated in exhibitor service manual. Move-out must be completed by hours stated in exhibitor service manual. Exhibitors are responsible for removal of all materials used in their display. Any exhibitor leaving materials after hours stated in exhibitor service manual will be charged for the materials' removal.

7. Losses or Damage

Exhibitor agrees that 2021 PPC-SOFE shall not be liable for any damage or liability of any kind or for any loss, damage or injury to persons or property during the term of this agreement, from any cause whatsoever by reason of use, occupation and enjoyment of exhibit space by Exhibitor or any person thereon with the consent of Exhibitor, and that Exhibitor will defend, indemnify and save harmless, 2021 PPC-SOFE from all liability whatsoever, on account of any such damage, or injury, whether or not caused by negligence of or breach of an obligation by Exhibitor or its employees or representatives. Exhibitor will be liable for all damages, or liability of any kind or for any loss, damage or injury to persons or any property during the show from any cause whatsoever by reason of use, occupation, and enjoyment of exhibit space.

8. Demonstrations

No demonstrations or solicitations shall be permitted outside of the Exhibitor's assigned space, and no signs or placards may be displayed on persons or otherwise outside exhibit spaces.

9. Compliance

The Exhibitor assumes all responsibility for compliance with all pertinent ordinances, regulations and codes of duly authorized local, State and federal governing bodies concerning fire, safety and health, together with the rules and regulations of the operators and/or owners of the property wherein the Show isheld.

10. Policy

It is further agreed that the Exhibitor will abide by and comply with rules and regulations concerning local customs that may apply, having agreements with the Show Facility or with authorized contractors employed by 2021 PPC-SOFE.

11. Management

The Exhibitor further agrees that the conditions, rules and regulations of the 2021 PPC-SOFE management are made a part of this contract and that said Exhibitor agrees to be bound by each and all of these rules and regulations, and that the management shall have the full power to interpret, amend and enforce all rules and regulations in the best interest of the Show.

12. Alteration of Booth Space

2021 PPC-SOFE management shall be entitled to alter the layout if, in their opinion, this is in the general interest of the Exhibition.







2021 PPC-SOFE EXHIBITOR REGISTRATION FORM

Use this form only if paying by check, otherwise you will enter this via the website			
COMPANY INFORMATION (as ye	ou wish it to appea	ar in Conference n	naterial)
Company Name:			
Company Contact:	Title:		Phone:
			Email:
Name of On-site Contact:		Cell Phone: (Or	n-site contact)
Mailing Address:			
City:	State:		Zip:
EXHIBITOR PACKAGE (Please s	elect all that app	oly)	
Single Booth (\$5000): Si	tandard Booth a	nd 2 Full Registr	rations
Preferences will be mad	e on a first come	e, first serve basi	is*
1 st Booth preference	:	2nd Booth	preference:
3 rd Booth preference: 4 th Booth preference:			
* If the booth layout and/or number of booths require modification in a significant fashion at the discretion of the 2021 PPC-SOFE management, the Exhibitors will be contacted, in order of receipt of contract application and required deposit, and be given the option of changing the assignment of space or offered a refund.			
Signature:			
Signature affirms agreement to payment terms and all requirements, restrictions, and obligations set forth in the PPC-SOFE Conference Prospectus which accompanied this application and any other rules and directives which at any time are issued by the conference in connection with the PPC-SOFE Conference and/or Downtown Denver Sheraton. Signature is required.			
PAYMENT TERMS:			
 Payment by Check (make payable 2021") or Credit Card via exhibit webpage 50% Deposit (\$2500) Due with Fagistration Full Payment Due by September 	or sign up Exhibitor	Send Paymen PPC SOFE 202 c/o IEEE MCE 445 Hoes Land Piscataway, N	1







